PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data			
1.1 Company STMicroelectronics International N.V		STMicroelectronics International N.V	
1.2 PCN No.		MDG/17/9977	
1.3 Title of PCN		Transfer assembly plant from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) for products in UFQFPN 5x5 & 7x7 packages	
1.4 Product Category		UFQFPN 5x5 and 7x7 packaged products	
1.5 Issue date		2017-02-17	

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	FRANK WOLINSKI	
2.1.2 Phone	+49 89460062287	
2.1.3 Email	frank.wolinski@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Michel BUFFA	
2.1.2 Marketing Manager	Daniel COLONNA	
2.1.3 Quality Manager	Pascal NARCHE	

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials		Stats ChipPAC Shanghai China (SCC), Stats ChipPAC Jiangyin China (JSCC)

4. Description of change		
	Old	New
4.1 Description	Current location : Stats ChipPAC Shanghai China (SCC)	Transfer from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) location. See more information on PCN 9977 – Additional information document attached.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Change lead shape : with neck design. See in PCN 9977 – Additional information document attached. No change in fit, function, reliability or process ability.	

5. Reason / motivation for change		
5.1 Motivation Due to Shanghai China site closure, production is relocated to Jiangyin China site. This Product Change Notification (PCN) concerns only UFQFPN 5x5 and 7x7 packa products.		
5.2 Customer Benefit	SERVICE CONTINUITY	

6. Marking of parts / traceability of change	
6.1 Description Traceability is described in PCN9977_Additional information attached documer	

7. Timing / schedule	
7.1 Date of qualification results	2017-05-26
7.2 Intended start of delivery	2017-06-26
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	9977 PCN9977_RERMCD1622- UQFN5x5_7x7 JSCC- MCD QA reliability plan.pdf		
8.2 Qualification report and qualification results		Issue Date	2017-02-17

9. Attachments (additional documentations)

9977 Public product.pdf 9977 PCN9977_Additional information.pdf 9977 PCN9977_RERMCD1622- UQFN5x5_7x7 JSCC- MCD QA reliability plan.pdf

10. Affected parts		
	10. 1 Current	10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32L151C6U6TR	
	STM32F031K6U6	
	STM32F051K6U6	
	STM32L052K6U6	
	STM32L052K8U6	
	STM32F051K4U6	

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